## 1.0 ELECTRICAL CHARACTERISTICS

#### Absolute Maximum Ratings†

Drain-to-Source Voltage	BV <sub>DSS</sub>
Drain-to-Gate Voltage	
Gate-to-Source Voltage	
Operating Ambient Temperature, T <sub>A</sub>	
Storage Temperature, T <sub>S</sub>	

**† Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

**Electrical Specifications:**  $T_A = 25$ °C unless otherwise specified. All DC parameters are 100% tested at 25°C unless otherwise stated. (Pulse test: 300 µs pulse, 2% duty cycle)

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	60		_	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 10 μA
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.8		3	V	$V_{GS} = V_{DS}$ , $I_D = 1 \text{ mA}$
Gate Body Leakage Current	I <sub>GSS</sub>			10	nA	$V_{GS}$ = ±15V, $V_{DS}$ = 0V
	I <sub>DSS</sub>			1	μA	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 48V
Zero-Gate Voltage Drain Current			_	1	mA	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 48V, T <sub>A</sub> = 125°C (Note 1)
On-State Drain Current	I <sub>D(ON)</sub>	75			mA	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V
Static Drain-to-Source On-State Resistance	D			5.3	Ω	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 75 mA
	R <sub>DS(ON)</sub>	_	_	5	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 500 mA

**Note 1:** Specification is obtained by characterization and is not 100% tested.

#### **AC ELECTRICAL CHARACTERISTICS**

Electrical Specifications: T <sub>A</sub> = 25°C unless otherwise specified. All AC parameters are not 100% sample tested.									
Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions			
Forward Transconductance	G <sub>FS</sub>	100	—	—	mmho	V <sub>DS</sub> = 10V, I <sub>D</sub> = 200 mA			
Input Capacitance	C <sub>ISS</sub>	_	—	60	pF				
Common-Source Output Capacitance	C <sub>OSS</sub>	-	_	25	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1 MHz			
Reverse Transfer Capacitance	C <sub>RSS</sub>		_	5	pF				
Turn-On Delay Time	t <sub>d(ON)</sub>	_	—	10	ns	V <sub>DD</sub> = 15V, I <sub>D</sub> = 500 mA,			
Turn-Off Delay Time	t <sub>d(OFF)</sub>	-	_	10	ns	R <sub>GEN</sub> = 25Ω			
DIODE PARAMETER									
Diode Forward Voltage Drop	V <sub>SD</sub>		0.85	—	V	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 200 mA ( <b>Note 1</b> )			

**Note 1:** All DC parameters are 100% tested at 25°C unless otherwise stated. (Pulse test: 300 µs pulse, 2% duty cycle)

## **TEMPERATURE SPECIFICATIONS**

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T <sub>A</sub>	-55		+150	°C	
Storage Temperature	Τ <sub>S</sub>	-55	_	+150	°C	
PACKAGE THERMAL RESISTANCE	•	•	•	•	<u> </u>	
3-lead TO-92	$\theta_{JA}$	_	132	_	°C/W	

Note 1: Mounted on an FR4 board; 25 mm x 25 mm x 1.57 mm

#### THERMAL CHARACTERISTICS

Package	I <sub>D</sub> ( <mark>Note 1</mark> ) (Continuous) (mA)	I <sub>D</sub> (Pulsed) (mA)	Power Dissipation at T <sub>C</sub> = 25°C (W)	I <sub>DR</sub> (Note 1) (mA)	I <sub>DRM</sub> (mA)
3-lead TO-92	200	500	1	200	500

Note 1:  $I_D$  (continuous) is limited by maximum  $T_J$ .

<sup>© 2021</sup> Microchip Technology Inc.

## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.

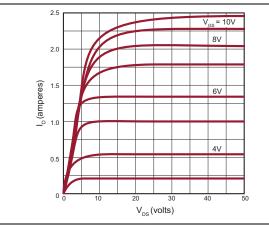


FIGURE 2-1: Output Characteristics.

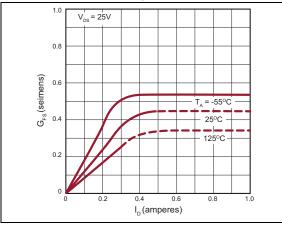


FIGURE 2-2: Transconductance vs. Drain Current.

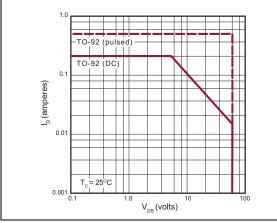
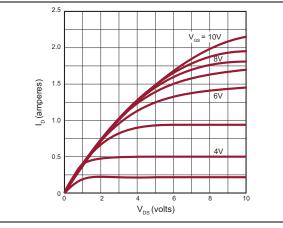


FIGURE 2-3: Maximum Rated Safe Operating Area.





Saturation Characteristics.

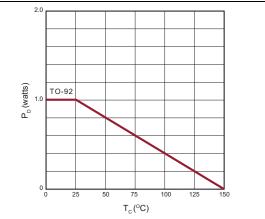


FIGURE 2-5:Power Dissipation vs. CaseTemperature.

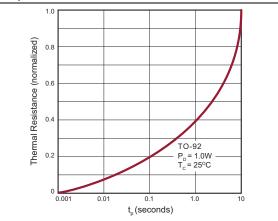
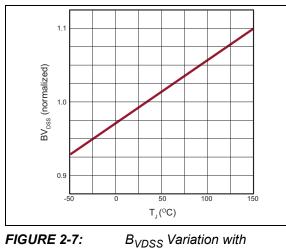


FIGURE 2-6: Characteristics.

Thermal Response





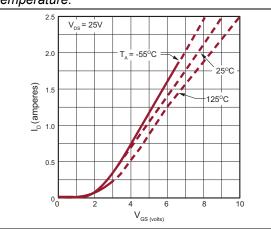


FIGURE 2-8:

Transfer Characteristics.

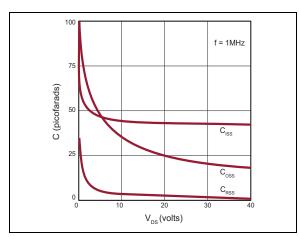
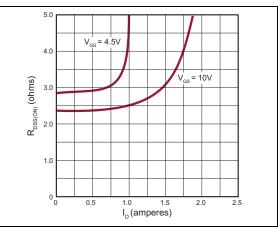


FIGURE 2-9: Capacitance vs. Drain-to-Source Voltage.





On-Resistance vs. Drain

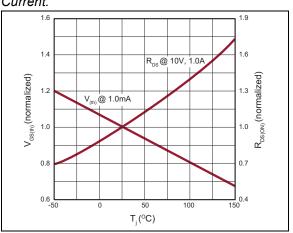


FIGURE 2-11:  $V_{GS(th)}$  and  $R_{DS}$  Variation with Temperature.

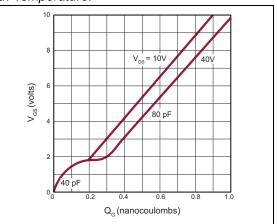


FIGURE 2-12: Characteristics.

Gate Drive Dynamic

#### 3.0 PIN DESCRIPTION

Table 3-1 shows the description of pins in 2N7000.Refer to Package Type for the location of the pins.

#### TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	Source	Source
2	Gate	Gate
3	Drain	Drain

#### 4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for 2N7000.

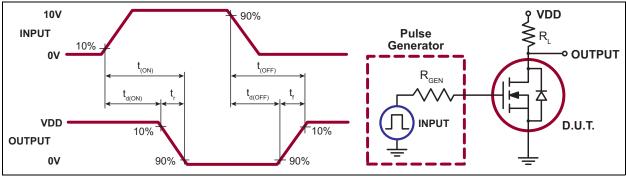


FIGURE 4-1: Switching Waveforms and Test Circuit.

#### TABLE 4-1: PRODUCT SUMMARY

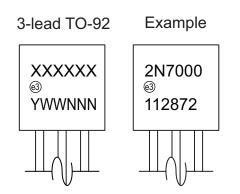
BV <sub>DSS</sub> /BV <sub>DGS</sub> (V)	R <sub>DS(ON)</sub> (Maximum) (Ω)	V <sub>GS(th)</sub> (Maximum) (mA)
60	5	75

<sup>© 2021</sup> Microchip Technology Inc.

# 2N7000

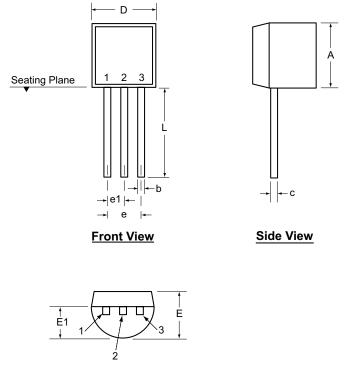
#### 5.0 PACKAGING INFORMATION

#### 5.1 Package Marking Information



Legend	:: XXX Y YY WW NNN @3 * (e4)	Product Code or Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC <sup>®</sup> designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package. Pre-plated
Note:	be carrie characters	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for product code or customer-specific information. Package may or e the corporate logo.

## 3-Lead TO-92 Package Outline (L/LL/N3)



**Bottom View** 

Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symb	ol	Α	b	с	D	E	E1	е	e1	L
	MIN	.170	.014 <sup>†</sup>	.014†	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
(	MAX	.210	.022†	.022†	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

\* This dimension is not specified in the JEDEC drawing.

*† This dimension differs from the JEDEC drawing. Drawings not to scale.* 

# 2N7000

NOTES:

#### APPENDIX A: REVISION HISTORY

#### **Revision A (February 2021)**

- Converted Supertex Doc# DSFP-2N7000 to Microchip D20005695A
- Removed the TO-92 N3 P002, P003, P005, P013, and P014 media types to align package specifications with the actual BQM
- Made minor text changes throughout the document

<sup>© 2021</sup> Microchip Technology Inc.

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	<u> </u>		- <u>x</u> - <u>x</u>	Exa	amples:	
Device	Packa Optio		Environmental Media Type	a)	2N7000-G:	N-Channel Enhancement-Mode, Vertical DMOS FET, 3-lead TO- 92,1000/Bag
Device:	2N7000	=	N-Channel Enhancement-Mode Vertical DMOS FET			
Package:	(blank)	=	3-lead TO-92			
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package			
Media Type:	(blank)	=	1000/Bag for a 3-lead TO-92 Package			

#### Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods being used in attempts to breach the code protection features of the Microchip devices. We believe that these methods require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Attempts to breach these code protection features, most likely, cannot be accomplished without violating Microchip's intellectual property rights.
- Microchip is willing to work with any customer who is concerned about the integrity of its code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not
  mean that we are guaranteeing the product is "unbreakable." Code protection is constantly evolving. We at Microchip are
  committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection
  feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or
  other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication is provided for the sole purpose of designing with and using Microchip products. Information regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WAR-RANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDI-RECT, SPECIAL, PUNITIVE, INCIDENTAL OR CONSEQUEN-TIAL LOSS, DAMAGE, COST OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

#### Trademarks

The Microchip name and logo, the Microchip logo, Adaptec, AnyRate, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, chipKIT, chipKIT logo, CryptoMemory, CryptoRF, dsPIC, FlashFlex, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PackeTime, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, APT, ClockWorks, The Embedded Control Solutions Company, EtherSynch, FlashTec, Hyper Speed Control, HyperLight Load, IntelliMOS, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, Temux, TimeCesium, TimeHub, TimePictra, TimeProvider, WinPath, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, IdealBridge, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, Inter-Chip Connectivity, JitterBlocker, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SMART-I.S., storClad, SQI, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, TSHARC, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries

 $\ensuremath{\mathsf{SQTP}}$  is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2021, Microchip Technology Incorporated, All Rights Reserved.

ISBN: 978-1-5224-7624-5

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.

© 2021 Microchip Technology Inc.



## Worldwide Sales and Service

#### AMERICAS

**Corporate Office** 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: http://www.microchip.com/ support

Web Address: www.microchip.com

Atlanta Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

**Boston** Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

Dallas Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Novi, MI Tel: 248-848-4000

Houston, TX Tel: 281-894-5983

Indianapolis Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

San Jose, CA Tel: 408-735-9110 Tel: 408-436-4270

Canada - Toronto Tel: 905-695-1980 Fax: 905-695-2078

DS20005695A-page 14

#### ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733

China - Beijing Tel: 86-10-8569-7000 China - Chengdu

Tel: 86-28-8665-5511 China - Chongqing Tel: 86-23-8980-9588

China - Dongguan Tel: 86-769-8702-9880

China - Guangzhou Tel: 86-20-8755-8029

China - Hangzhou Tel: 86-571-8792-8115

China - Hong Kong SAR Tel: 852-2943-5100

China - Nanjing Tel: 86-25-8473-2460

China - Qingdao Tel: 86-532-8502-7355

China - Shanghai Tel: 86-21-3326-8000

China - Shenyang Tel: 86-24-2334-2829

China - Shenzhen Tel: 86-755-8864-2200

China - Suzhou Tel: 86-186-6233-1526

China - Wuhan Tel: 86-27-5980-5300

China - Xian Tel: 86-29-8833-7252

China - Xiamen Tel: 86-592-2388138 China - Zhuhai

Tel: 86-756-3210040

#### ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444

India - New Delhi Tel: 91-11-4160-8631 India - Pune

Tel: 91-20-4121-0141 Japan - Osaka

Tel: 81-6-6152-7160 Japan - Tokyo

Tel: 81-3-6880- 3770 Korea - Daegu

Tel: 82-53-744-4301 Korea - Seoul

Tel: 82-2-554-7200

Malaysia - Kuala Lumpur Tel: 60-3-7651-7906

Malaysia - Penang Tel: 60-4-227-8870

Philippines - Manila Tel: 63-2-634-9065

Singapore Tel: 65-6334-8870

Taiwan - Hsin Chu

Tel: 886-3-577-8366 Taiwan - Kaohsiung Tel: 886-7-213-7830

Taiwan - Taipei Tel: 886-2-2508-8600

Thailand - Bangkok Tel: 66-2-694-1351

Vietnam - Ho Chi Minh Tel: 84-28-5448-2100

Fax: 31-416-690340

Tel: 47-7288-4388

Tel: 40-21-407-87-50

Sweden - Gothenberg Tel: 46-31-704-60-40

Sweden - Stockholm Tel: 46-8-5090-4654

**UK - Wokingham** 

© 2021 Microchip Technology Inc. 02/28/20

Tel: 49-7131-72400 Germany - Karlsruhe Tel: 49-721-625370

EUROPE

Austria - Wels

Tel: 43-7242-2244-39

Tel: 45-4485-5910

Fax: 45-4485-2829

Tel: 358-9-4520-820

Tel: 33-1-69-53-63-20

Fax: 33-1-69-30-90-79

Germany - Garching

Tel: 49-2129-3766400

Germany - Heilbronn

Tel: 49-8931-9700

Germany - Haan

Finland - Espoo

France - Paris

Fax: 43-7242-2244-393

**Denmark - Copenhagen** 

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Germany - Rosenheim Tel: 49-8031-354-560

Israel - Ra'anana Tel: 972-9-744-7705

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Padova Tel: 39-049-7625286

**Netherlands - Drunen** Tel: 31-416-690399

Norway - Trondheim

Poland - Warsaw Tel: 48-22-3325737

**Romania - Bucharest** 

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Tel: 44-118-921-5800 Fax: 44-118-921-5820